

SOT117-2

plastic dual in-line package; 28 leads (600 mil); long body

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DIP28
Package type industry code	DIP28
Package style descriptive code	DIP (dual in-line package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	051G06
JEDEC package outline code	MS-011
JEITA package outline code	SC-510-28
Mounting method type	T (through-hole mount)
Issue date	12-3-2003

Table 1. Package summary

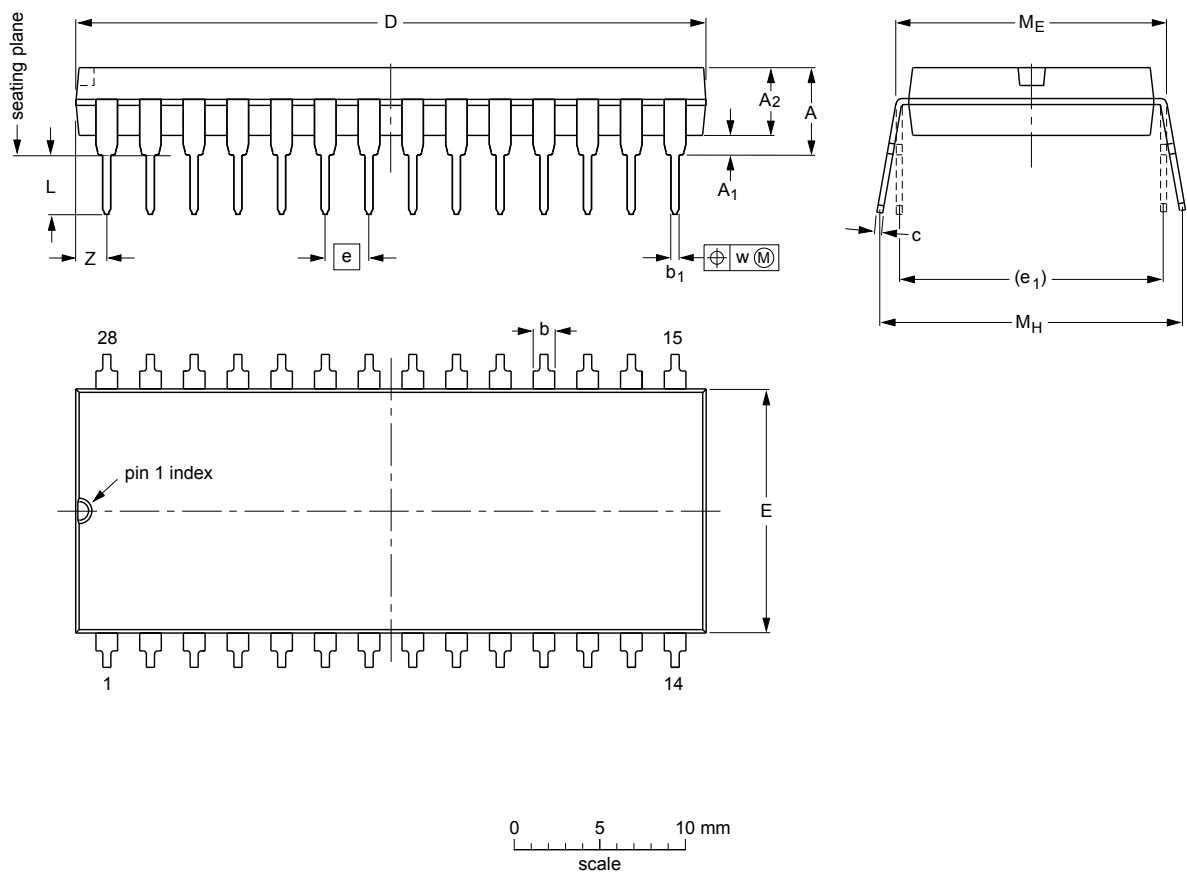
Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		35.94	-	36.51	37.08	mm
E	package width		13.84	-	14.03	14.22	mm
A	seated height		[tbd]	-	5.08	5.08	mm
A ₂	package height		[tbd]	-	3.94	3.94	mm
n ₂	actual quantity of termination		-	-	28	-	



2. Package outline

DIP28: plastic dual in-line package; 28 leads (600 mil); long body

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DIMENSIONS (mm dimensions are derived from the original inch dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	5.08	0.51	3.94	1.63 1.14	0.56 0.43	0.38 0.25	37.08 35.94	14.22 13.84	2.54	15.24	3.51 3.05	15.75 15.24	17.65 15.24	0.25	2.1
inches	0.2	0.02	0.155	0.064 0.045	0.022 0.017	0.015 0.010	1.460 1.415	0.560 0.545	0.1	0.6	0.138 0.120	0.62 0.60	0.695 0.600	0.01	0.083

Note
1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT117-2	051G06	MS-011	SC-510-28			99-12-27 03-03-12

Fig. 1. Package outline DIP28 (SOT117-2)

3. Legal information

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